



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD80N04S3-06	Issued	17. February 2022
MA#	MA005698210		
Package	PG-TO252-3-11	Weight*	372.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.047	0.82	0.82	8181	8181
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		578	
	non noble metal	copper	7440-50-8	215.017	57.73	57.81	577243	577994
wire	non noble metal	aluminium	7429-90-5	5.862	1.57	1.57	15737	15737
encapsulation	inorganic material	zinc oxide	1314-13-2	1.225	0.33		3288	
	miscellaneous	miscellaneous	-	6.124	1.64		16442	
	plastics	epoxy resin	-	18.373	4.93		49325	
	inorganic material	silicon dioxide	60676-86-0	96.765	25.98	32.88	259780	328835
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10041	10041
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.055	0.01		148	
	noble metal	silver	7440-22-4	0.069	0.02		185	
	non noble metal	lead	7439-92-1	2.638	0.71	0.74	7082	7415
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51485	51552
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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